

APDS-9120

Integrated Optical Proximity Sensors



Data Sheet



Description

Avago's APDS-9120 is an integrated optical proximity sensor that combines built-in signal conditioning and space-saving packaging technology.

This integrated sensor provides ease of use, as it eliminates design efforts required in implementing external LED drivers, signal filtering and amplification, sunlight and ambient light immunity and LED stuck high protection circuit.

APDS-9120 is designed to be a robust proximity sensor. It has artificial light immunity and operates in sunlight exposure. Both analog and/or digital output options are available.

To maximize power savings and battery life in applications such as portable or battery-operated devices, APDS-9120 has a shutdown mode feature. With an external limiting resistor, the LED current of the optical proximity sensors can be configured to various levels. The pulse width, burst rate, duty cycle and frequency can be controlled to minimize power consumption. These features make it ideal for low power mobile and handheld devices.

Application Support Information

The Application Engineering Group is available to assist you with the application design associated with APDS-9120 module. You can contact them through your local sales representatives for additional details.

Features

- Small form factor with conditioning IC, emitter and detector integrated into one single package
 - H1.1mm x W4.4mm x L4.4mm
- Low power consumption
 - LED pulse width control
 - Low shut down current
 - External LED drive-current control
- Shutdown current 1 μ A max
- Supply voltage : 2.4 V to 3.6 V
- Typical detection distance 30mm based on Kodak 18% grey card
- Artificial light immunity
- Operational in sunlight conditions
- Analog & Digital output available
 - Built in hysteresis comparator for digital output
- LED stuck Hi protection

Applications

- PDA and mobile phones
- Portable and Handheld devices
- Personal Computers/Notebooks
- Contactless Switches

Ordering Information

Part Number	Package Type	Shipping Option
APDS-9120-020	Tape & Reel	2500

Absolute Maximum Ratings (Ta=25°C)

Parameter	Symbol	Min.	Max.	Units	Conditions
Supply Voltage	V _{CC}	0	4.0	V	
Peak LED Current	I _{LEDpk}	0	500	mA	Pulsed at 12.5% Duty-cycle
Reflow Soldering Temperature			260	°C	
Input Logic Voltage	V _I	0	4.0	V	

Recommended Operating Conditions

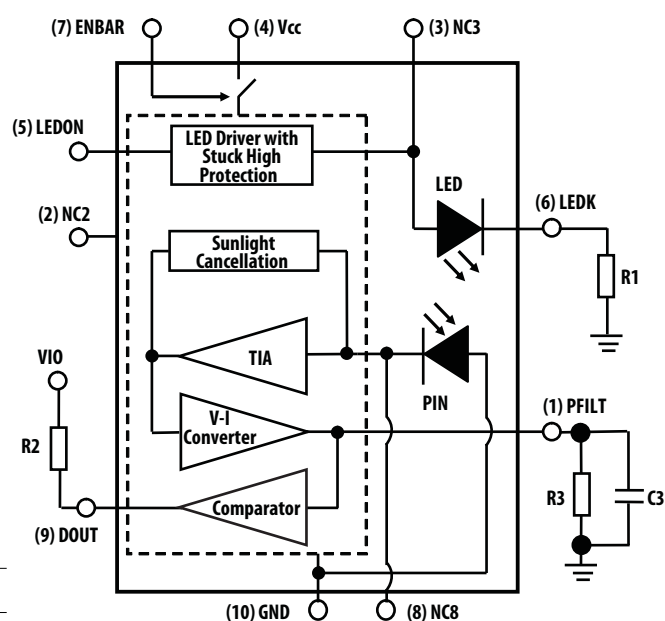
Parameter	Symbol	Min.	Max.	Units	Conditions
Operating Temperature	T _A	-40	85	°C	
Storage Temperature	T _S	-40	100	°C	
Supply Voltage	V _{CC}	2.4	3.6	V	

Electrical & Optical Specifications (Ta=25°C)

Parameters	Symbol	Min.	Typ.	Max.	Units	Conditions
Input						
Logic High Voltage, LEDON	V _{IH}	1.6	–	V _{CC}	V	
Logic High Voltage, ENB	V _{IH}	1.4	–	V _{CC}	V	For V _{CC} = 2.4V
		1.5	–	V _{CC}	V	For 2.4 < V _{CC} ≤ 3V
		1.7	–	V _{CC}	V	For 3 < V _{CC} ≤ 3.6V
Logic Low Voltage, LEDON	V _{IL}	0	–	0.3	V	
Logic Low Voltage, ENB	V _{IL}	0	–	0.3	V	
Logic High Input Current, LEDON	I _{IH}	–	0.1	1	μA	V _I ≥ V _{IH}
Logic High Input Current, ENB	I _{IH}	–	0.1	1	μA	V _I ≥ V _{IH}
Logic Low Input Current, LEDON	I _{IL}	–	0.1	1	μA	V _I ≤ V _{IL}
Logic Low Input Current, ENB	I _{IL}	–	0.1	1	μA	V _I ≤ V _{IL}
Shutdown Current	I _{SD}	–	0.3	1	μA	V _{CC} = 3V, ENB = 3V
Idle Current	I _{CC}	–	500	650	μA	V _{CC} = 3V, ENB = 0V
Output						
Analog Output	V _{PFILT}	1.25	1.9	2.55	V	V _{CC} = 3V, ENB = 0V, LEDON = 10 kHz, 50% DC, Continuous pulses; R3 = 1Mohm, C3 = 3.3nF; Kodak 18% grey card at detectable distance = 10mm from the APDS-9120
Digital Output	V _{OL}	0	–	0.3	V	I _{DOUT(Low)} = 2mA, V _{CC} = 3V
Rise Time(DOUT)	T _R	–	1	–	μs	V _{CC} = 3V, R2 = 10kΩ, Frequency = 10kHz
Fall Time(DOUT)	T _F	–	1	–	μs	V _{CC} = 3V, R2 = 10kΩ, Frequency = 10kHz
Transmitter						
Max I _{LED} Pulse Width	Max-PW	–	120	–	μs	V _{CC} = 3V, ENB = 0V
I _{LED} Peak Pulse Current	I _{LEDpk}	85	120	155	mA	V _{CC} = 3V, R1 = 10Ω
Hysterisis Comparator						
Hysterisis	V _{HYS}	–	40	–	mV	V _{CC} = 3V
Threshold Voltage	V _{TH}	–	655	–	mV	V _{CC} = 3V
Ambient light tolerance			100k	–	lux	Sun light
			10K	–		Incandescent
			5K	–		Fluorescent
			10K	–		Halogen

A schematic diagram of a rectangular arena with a black border. The arena is divided into a large square area on the left and a smaller rectangular area on the right. The large square area has a black border and a small black square in the bottom-left corner. The smaller rectangular area has a black border and a small black square in the bottom-left corner. The arena is surrounded by a black border. The arena is labeled with numbers 1 through 10 at the corners and midpoints of the sides.

APDS-9120 Internal Block Diagram



Typical Characteristics

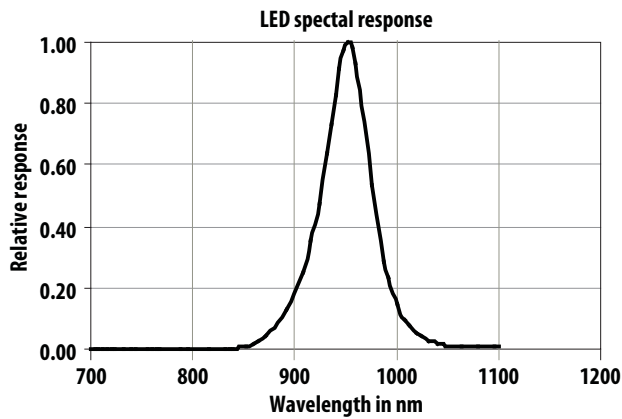


Figure 1. LED emitting spectrum

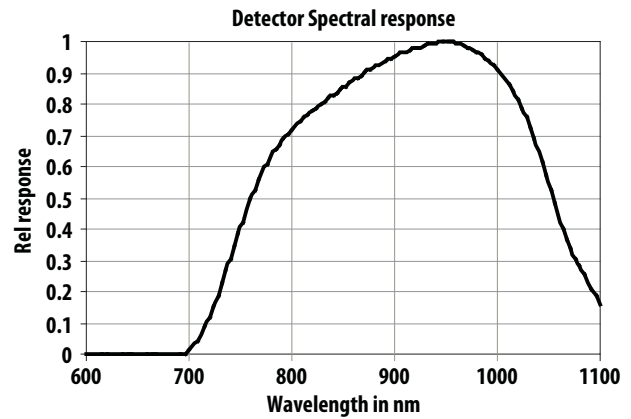


Figure 2. PIN spectral sensitivity

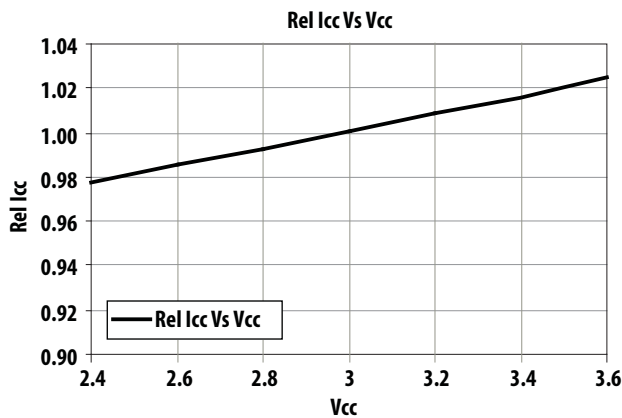


Figure 3. Relative supply current over supply voltage

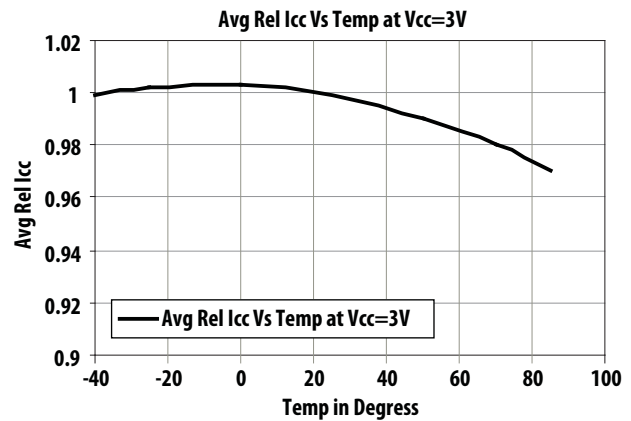


Figure 4. Average relative supply current over temperature

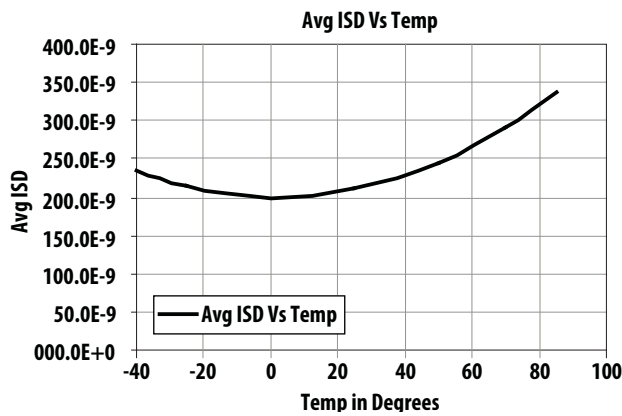


Figure 5. Average shutdown current over temperature

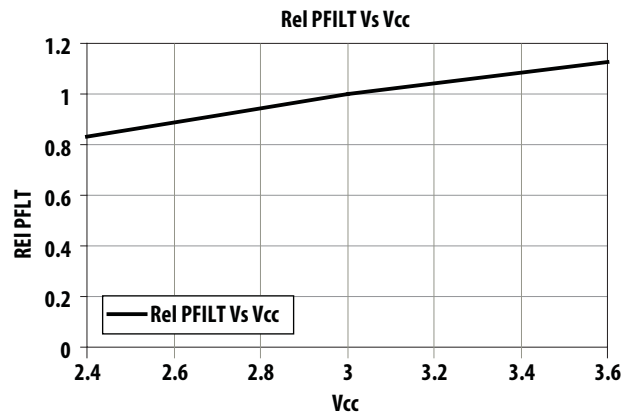


Figure 6. Relative output PFILT over supply voltage

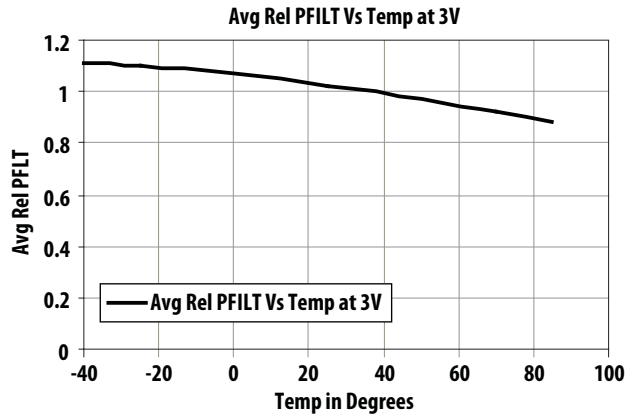


Figure 7. Average relative output PFILT over temperature

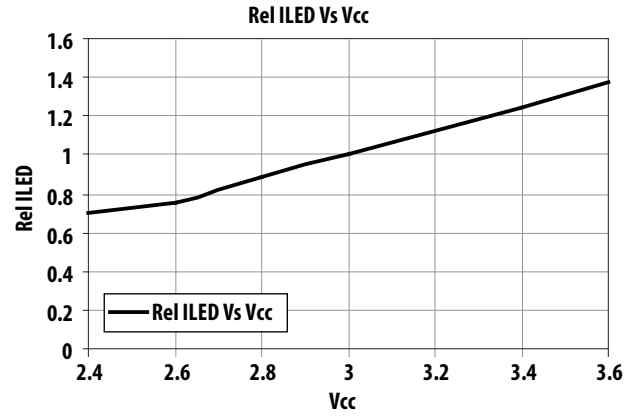


Figure 8. Relative ILED current over temperature

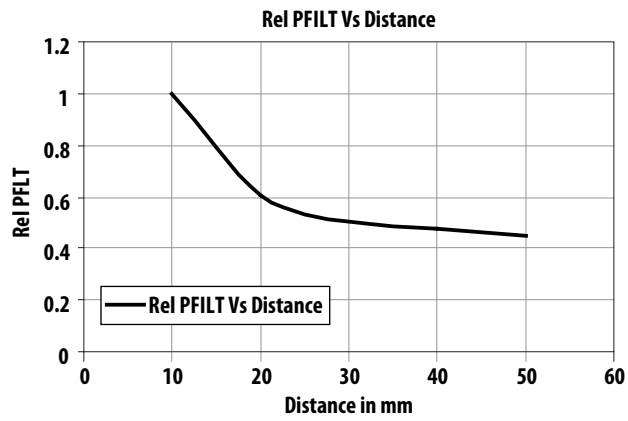


Figure 9. Relative output PFILT over detection distance

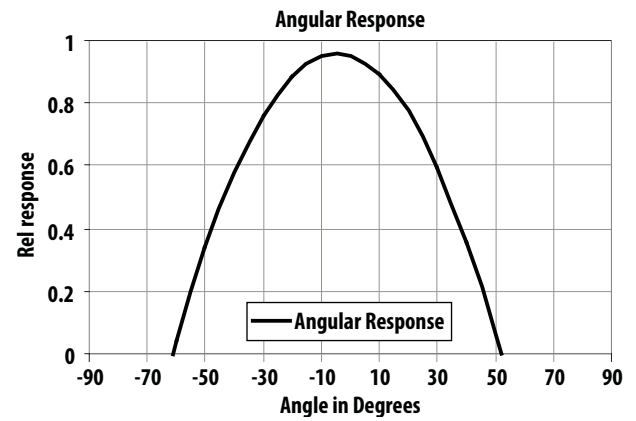
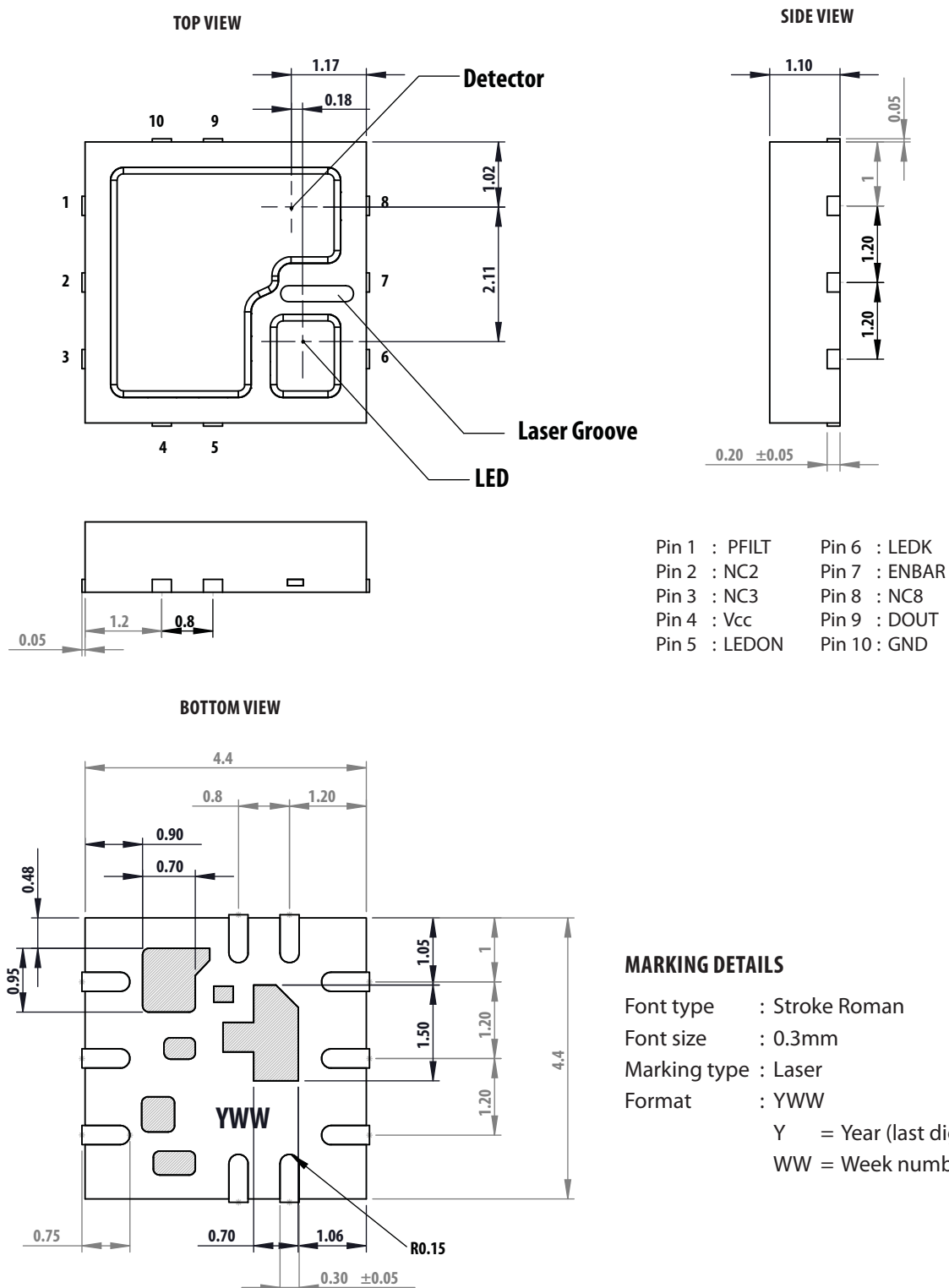


Figure 10. Angular response

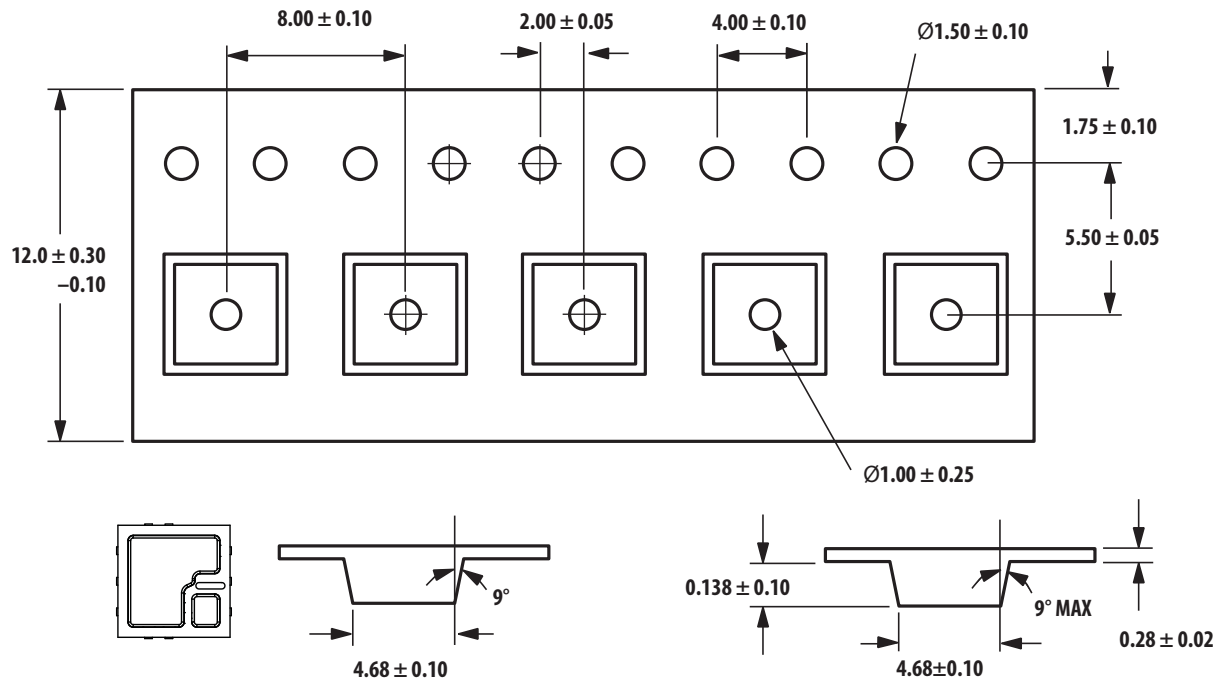
APDS-9120 Package Dimensions



Notes:

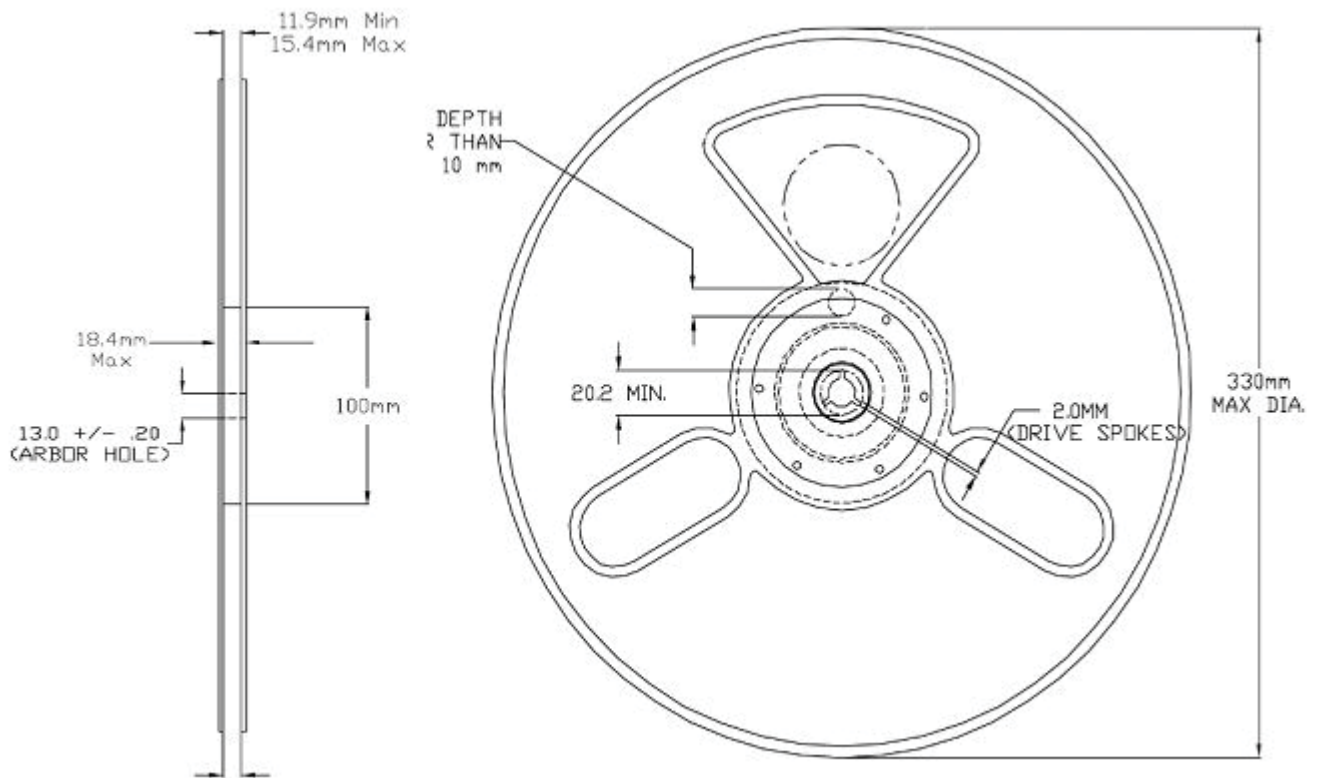
1. All dimensions are in millimeters. Dimension tolerance is ± 0.1 mm unless otherwise stated.
2. This package contains no lead.
3. Do NOT connect the bottom exposed pads.
4. No PCB circuitry under the device.

Tape and Reel Dimensions



Dimensions in mm

Reel Drawings



1.3 Recommended Metal Solder Stencil Aperture

It is recommended that a 0.11 mm thick stencil be used for solder paste printing. Aperture opening for shield pad is 0.8mm x 0.4mm (as per land pattern). This is to ensure adequate printed solder paste volume and no shorting.

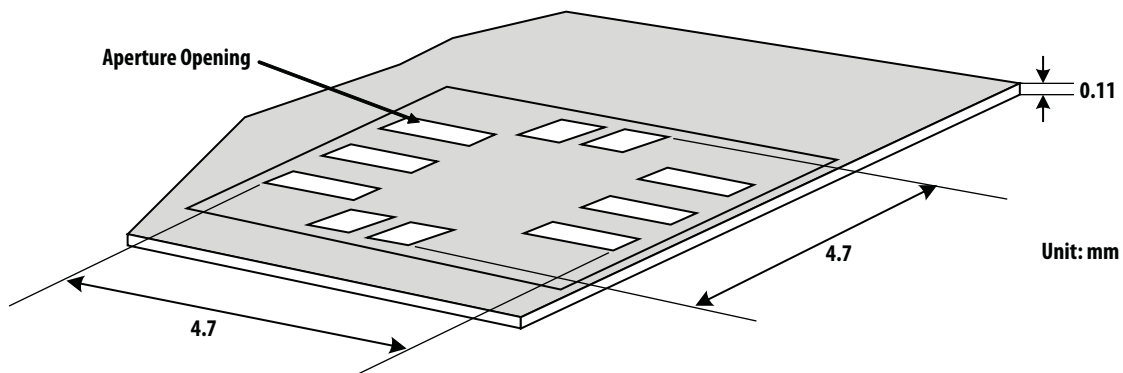


Figure 13. Solder Stencil Aperture

1.4 Adjacent Land Keepout and Solder Mask Areas

Adjacent land keep-out is the maximum space occupied by the unit relative to the land pattern. There should be no other SMD components within this area.

The minimum solder resist strip width required to avoid solder bridging adjacent pads is 0.2 mm.

Note: Wet/Liquid Photo-Imageable solder resist/mask is recommended.

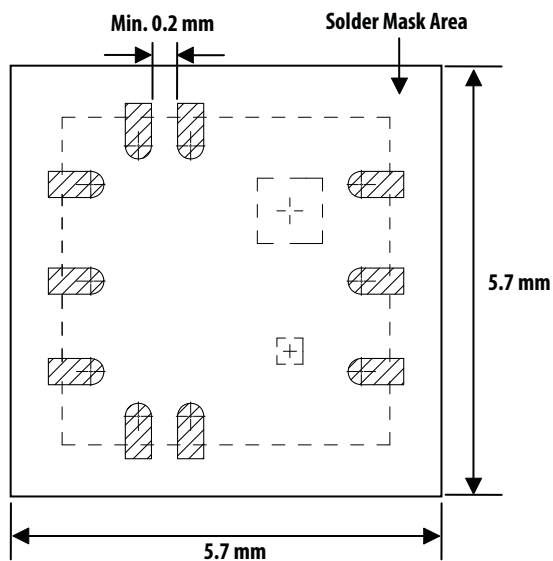
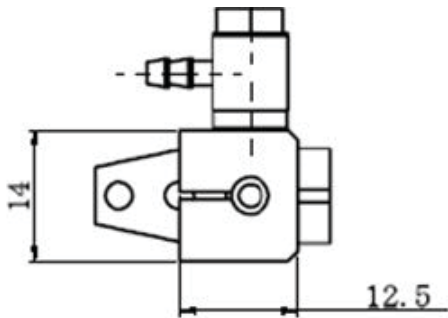


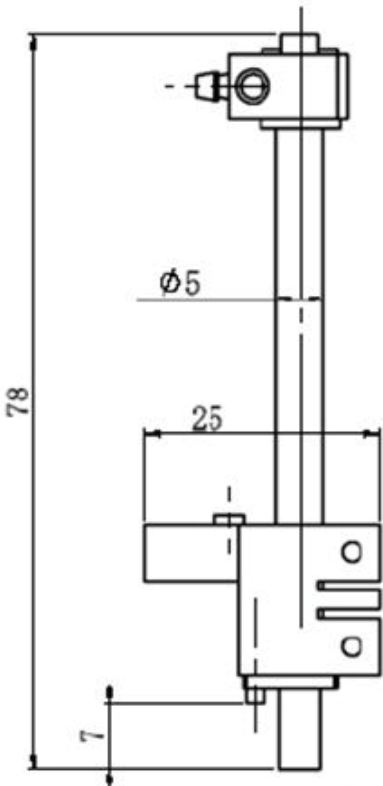
Figure 14. Adjacent Land Keepout and Solder Mask Areas

Recommended Pickup Nozzle

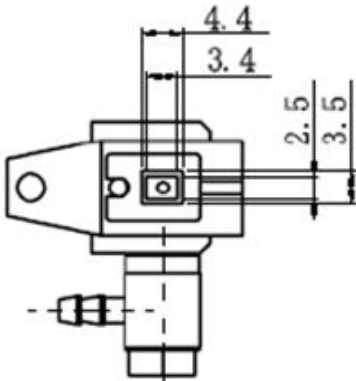
TOP VIEW



SIDE VIEW

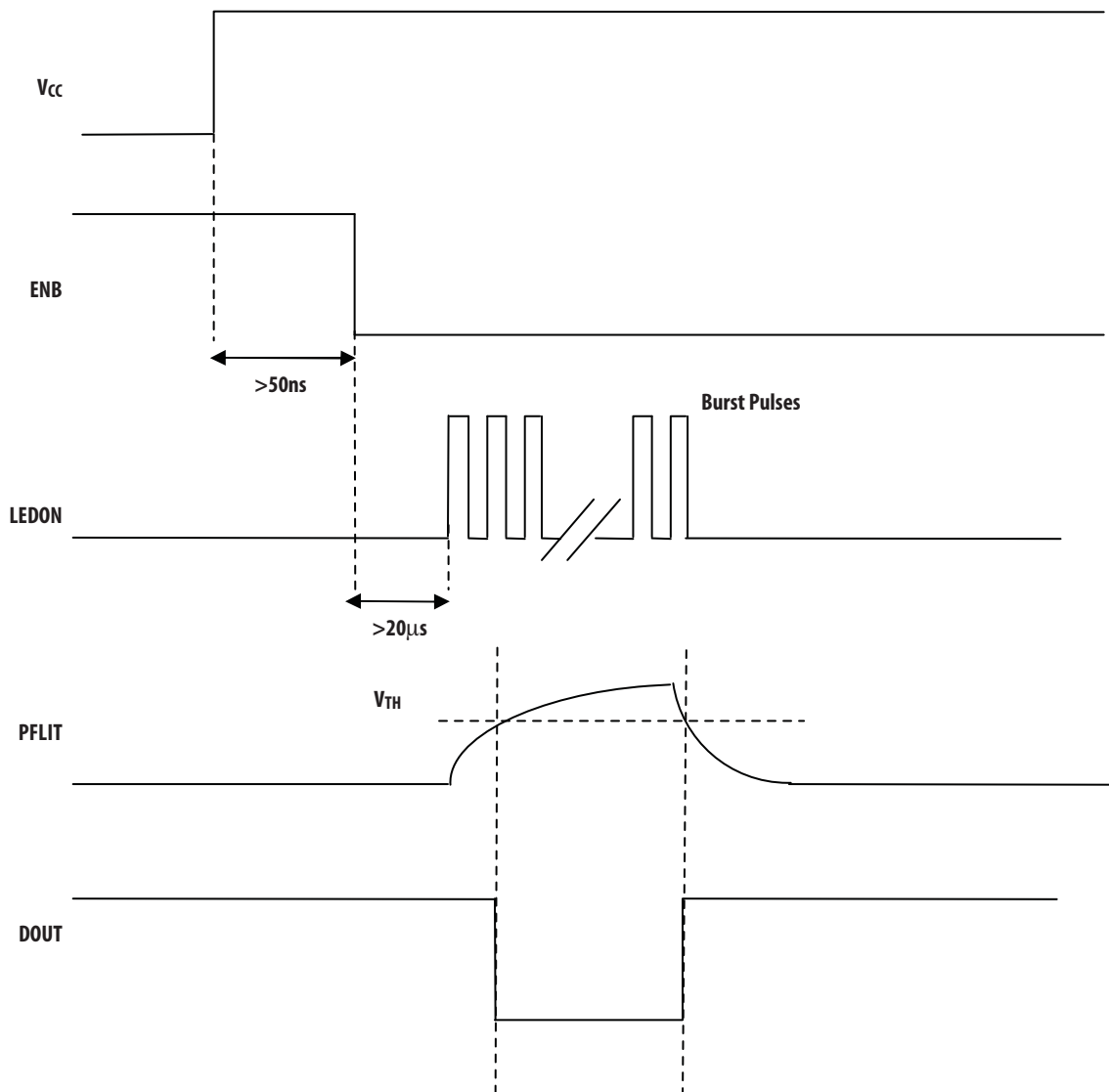


BOTTOM VIEW



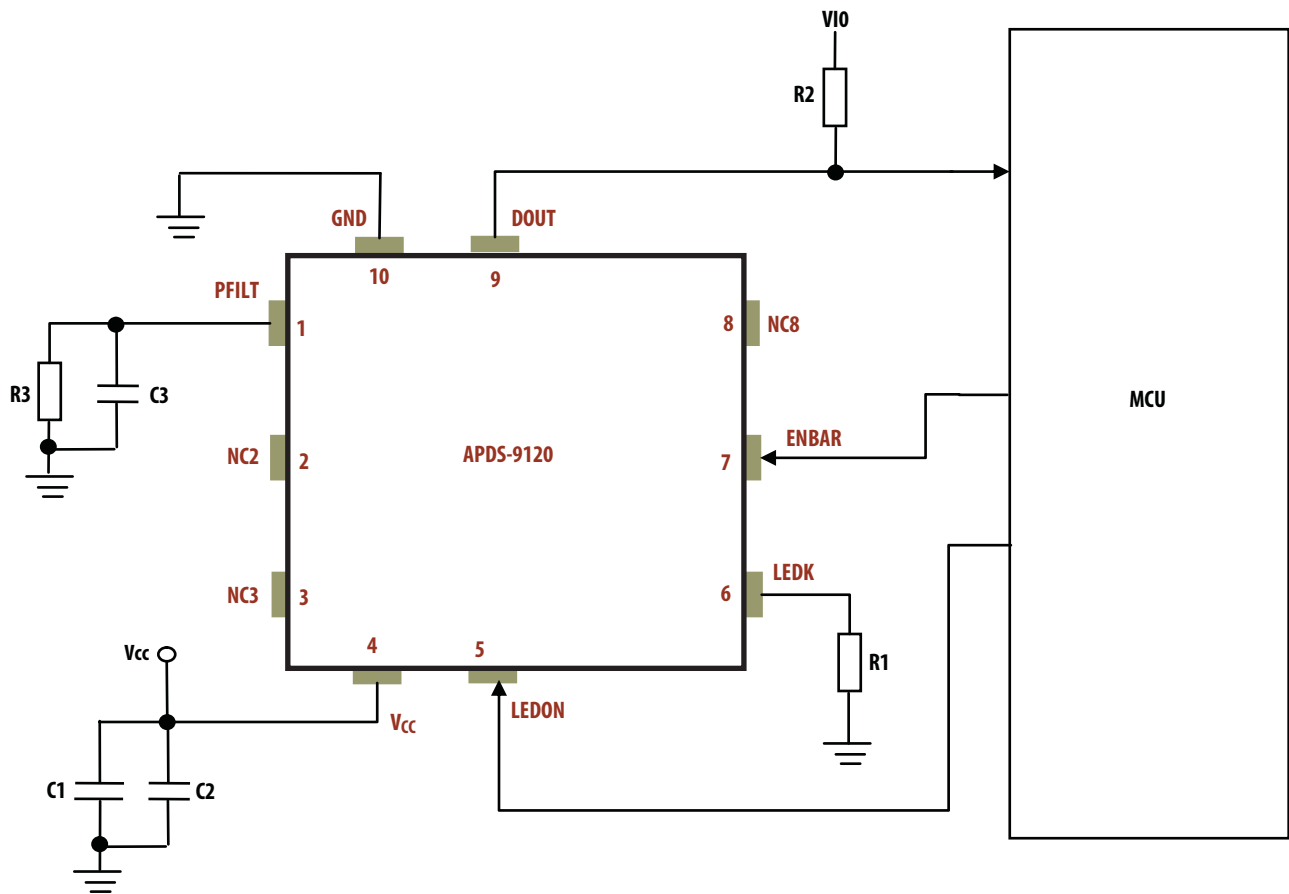
Dimension in mm

APDS-9120 Typical Timing Waveforms



Note:
Pulses at LEDON can only be activated at least $20\mu\text{s}$ after ENB turn from high to low.

Typical Application Circuit

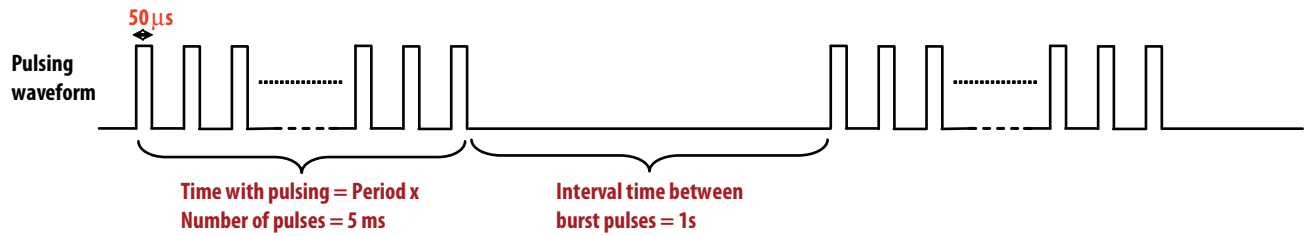


Note:

1. Do NOT connect the NC (no connect) pins

Recommended Operating Condition

(a) Recommended burst pulse to drive LEDON (pin5) :



R1	10 ohm
Iled (typ)	120mA
Number of Burst Pulse	50
Period of Burst Pulse	100µs
Duty Cycle of Burst Pulse	50%
Interval Between Burst Pulse	1 sec

(b) Recommended components used:

Component	Recommended Values
R1	10 ohm
R2	10k ohm
R3	1M ohm
C1	100nF, Ceramic
C2	6.8µF, Tantalum
C3	3.3nF, Ceramic

Note:

1. R3 and C3 are integrated circuit that can be adjusted to meet desired detectable distance
2. Detectable distance is the distance when the object is first detected to trigger a "LOW" at DOUT (pin9).

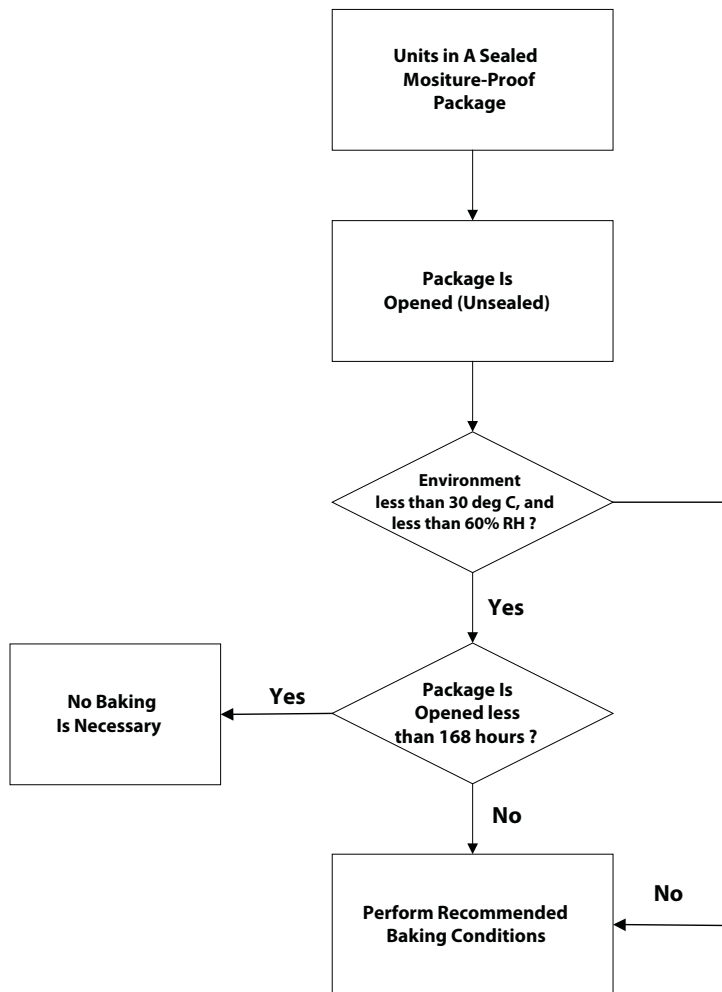
Optical Window Design Reference

Please refer to AN 5464: APDS-9120-020 Integrated Optical Proximity Sensor Window Guide Design.

<http://www.avagotech.com/docs/AV02-2401EN/>

Moisture Proof Packaging

All APDS-9120 options are shipped in moisture proof package. Once opened, moisture absorption begins. This part is compliant to JEDEC MSL 3.



Baking Conditions:

Package	Temperature	Time
In Reel	60±C	48 hours
In Bulk	100±C	4 hours

If the parts are not stored in dry conditions, they must be baked before reflow to prevent damage to the parts.

Baking should only be done once.

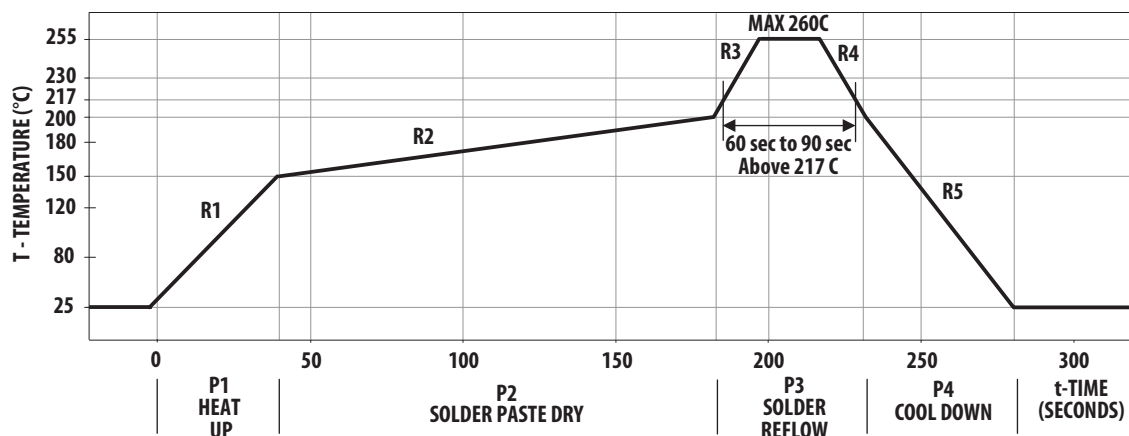
Recommended Storage Conditions:

Storage Temperature	100C to 300C
Relative Humidity	below 60% RH

Time from unsealing to soldering:

After removal from the bag, the parts should be soldered within 168 hours if stored at the recommended storage conditions. If times longer than 168 hours are needed, the parts must be stored in a dry box.

Recommended Reflow Profile



Process Zone	Symbol	ΔT	Maximum $\Delta T/\Delta \text{time}$ or Duration
Heat Up	P1, R1	25°C to 150°C	3°C/s
Solder Paste Dry	P2, R2	150°C to 200°C	100s to 180s
Solder Reflow	P3, R3	200°C to 260°C	3°C/s
	P3, R4	260°C to 200°C	-6°C/s
Cool Down	P4, R5	200°C to 25°C	-6°C/s
Time maintained above liquidus point, 217°C		> 217°C	60s to 120s
Peak Temperature		260°C	–
Time within 5°C of actual Peak Temperature		–	20s to 40s
Time 25°C to Peak Temperature		25°C to 260°C	8mins

The reflow profile is a straight-line representation of a nominal temperature profile for a convective reflow solder process. The temperature profile is divided into four process zones, each with different $\Delta T/\Delta \text{time}$ temperature change rates or duration. The $\Delta T/\Delta \text{time}$ rates or duration are detailed in the above table. The temperatures are measured at the component to printed circuit board connections.

In **process zone P1**, the PC board and component pins are heated to a temperature of 150°C to activate the flux in the solder paste. The temperature ramp up rate, R1, is limited to 3°C per second to allow for even heating of both the PC board and component pins.

Process zone P2 should be of sufficient time duration (100 to 180 seconds) to dry the solder paste. The temperature is raised to a level just below the liquidus point of the solder.

Process zone P3 is the solder reflow zone. In zone P3, the tem-

perature is quickly raised above the liquidus point of solder to 260°C (500°F) for optimum results. The dwell time above the liquidus point of solder should be between 60 and 90 seconds. This is to assure proper coalescing of the solder paste into liquid solder and the formation of good solder connections. Beyond the recommended dwell time the intermetallic growth within the solder connections becomes excessive, resulting in the formation of weak and unreliable connections. The temperature is then rapidly reduced to a point below the solidus temperature of the solder to allow the solder within the connections to freeze solid.

Process zone P4 is the cool down after solder freeze. The cool down rate, R5, from the liquidus point of the solder to 25°C (77°F) should not exceed 6°C per second maximum. This limitation is necessary to allow the PC board and component pins to change dimensions evenly, putting minimal stresses on the component.

It is recommended to perform reflow soldering no more than twice.

For product information and a complete list of distributors, please go to our web site: www.avagotech.com